

**In The Claims**

Please cancel claims 1-36, without prejudice or disclaimer and add the following new claims 37-52:

37. (New) A circuit component built-in module comprising:  
an insulating substrate formed of a mixture comprising an inorganic filler and a thermosetting resin;  
a plurality of wiring patterns formed on at least one principal plane of the insulating substrate;  
an active component buried in the insulating substrate and electrically connected to at least one of the wiring patterns; and  
a passive component buried in the insulating substrate and electrically connected to at least one of the wiring patterns;  
wherein the active component is electrically connected to the passive component by the wiring patterns.

38. (New) A circuit component built-in module according to claim 37, comprising an inner via formed in the insulating substrate and electrically connected to the wiring patterns.

39. (New) A circuit component built-in module according to claim 37, wherein 70 wt % to 95 wt % of the mixture comprises the inorganic filler and the thermosetting resin.

40.(New) A circuit component built-in module according to claim 37, wherein the wiring patterns are formed on the principal plane and in an internal portion of the insulating substrate.

41. (New) A circuit component built-in module according to claim 38, wherein the inner via is formed of a conductive resin composition.

42. (New) A circuit component built-in module according to claim 37, wherein the circuit component is shielded from external air by the insulating substrate.

43. (New) A circuit component built-in module according to claim 37, wherein the thermosetting resin comprises at least one thermosetting resin selected from the group consisting of an epoxy resin, a phenol resin and a cyanate resin.

44. (New) A circuit component built-in module according to claim 37, wherein the inorganic filler comprises at least one inorganic filler selected from the group consisting of  $\text{Al}_2\text{O}_3$ ,  $\text{MgO}$ ,  $\text{BN}$ ,  $\text{AlN}$  and  $\text{SiO}_2$ .

45. (New) A circuit component built-in module according to claim 37, wherein an average particle diameter of the inorganic filler is  $0.1\mu\text{m}$  to  $100\mu\text{m}$ .

46. (New) A circuit component built-in module according to claim 37, wherein the wiring patterns comprise at least one conductive substance selected from the group consisting of copper and a conductive resin composition.

47. (New) A circuit component built-in module according to claim 37, wherein the wiring patterns comprise lead frames formed by etching or stamping.

48. (New) A circuit component built-in module according to claim 37, wherein the circuit component comprises at least one component selected from the group consisting of a chip resistor, a chip capacitor and a chip inductor.

49. (New) A circuit component built-in module according to claim 37, wherein the mixture further comprises at least one additive selected from the group consisting of a dispersant, a coloring agent, a coupling agent and a releasing agent.

50. (New) A circuit component built-in module according to claim 37, wherein the insulating substrate has a coefficient of linear expansion of  $8 \times 10^{-6}/^\circ\text{C}$  to  $20 \times 10^{-6}/^\circ\text{C}$  and a heat conductivity of  $1\text{w/mK}$  to  $10\text{w/mK}$ .

51. (New) A circuit component built-in module according to claim 37, wherein the active component comprises a semiconductor bare chip, and the semiconductor bare chip is flip-chip bonded onto the wiring pattern.

52. (New) A circuit component built-in module according to claim 37, wherein the conductive resin composition comprises metal particles of at least one metal selected from the group consisting of gold, silver, copper and nickel as a conductive component, and an epoxy resin as a resin component.